



Materials Development and Potential Applications of Ceramics

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Message from the Guest Editors

In recent years, the use of ceramics in science and industry has become increasingly widespread for their important advantages over metals and polymers. Applications for ceramic materials have been found in electronic devices, energy devices, aerospace industry, automotive industry, corrosion-resistant coatings, biomedical engineering, and so on. Every year, new design concepts, manufacturing technologies, and materials are rapidly developed to meet emerging applications in so many industries. We believe this Special Issue will become an international forum for exchanging ideas on recent advances in the concept design, synthesis, characterizations, and applications of novel and advanced ceramic materials.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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